

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc1661cn8#pbf

(Engineering Calculation)

PDIP

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**TOTAL MASS (g) : 0.498561**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001873	1000000	3756.80981445		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.149760	975000	300384.3125		
		Iron (Fe)	7439-89-6	0.003686	24000	7393.2734375		
		Phosphorus (P)	7723-14-0	0.000046	300	92.2654876709		
		Zinc (Zn)	7440-66-6	0.000108	700	216.623321533		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.153600</b>	<b>1000000</b>	<b>308086.5</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.012410	1000000	24892.2050781		
		<b>External Plating Total:</b>				<b>0.012410</b>	<b>1000000</b>	<b>24892.2050781</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001228	1000000	2463.08740234		
<b>Internal Plating Total:</b>				<b>0.001228</b>	<b>1000000</b>	<b>2463.08740234</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000661	750000	1325.81494141		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000220	250000	441.269714355		
<b>Die Attach Total:</b>				<b>0.000881</b>	<b>1000000</b>	<b>1767.0847168</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.044334	135000	88923.875		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.282424	860000	566478		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.001642	5000	3293.47680664		
		<b>Encapsulation Total:</b>				<b>0.328400</b>	<b>1000000</b>	<b>658695.3125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000169	1000000	338.975402832		
					<b>TOTAL MASS (g) :</b>	<b>0.498561</b>		